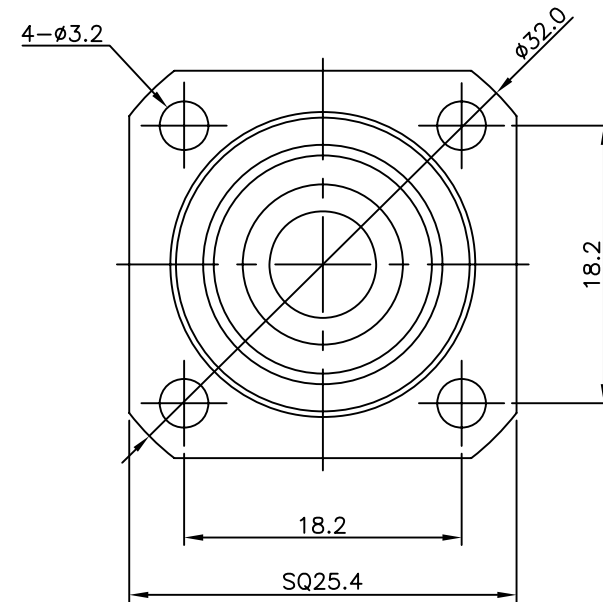
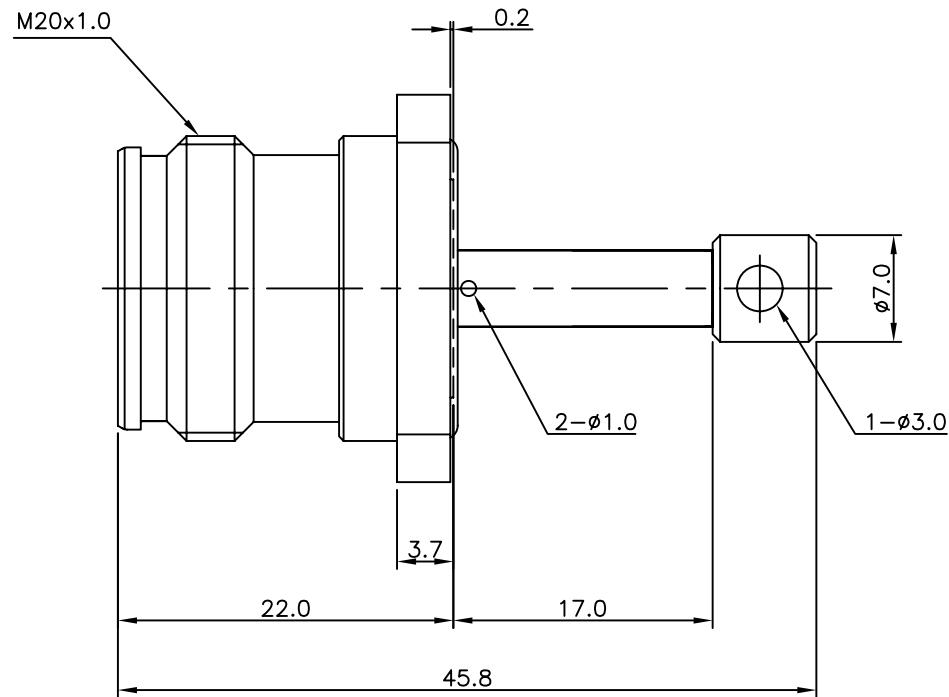


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2019. 09. 09.



9	JACK	1	MBsBD C3604BD-F	Silver Plate (3μm)	DJA00228-5/6
8	INSULATOR	1	TEFLON		DIN03082-N/2
7	INSULATOR	1	TEFLON		DIN03081-N/1
6	INSULATOR	1	TEFLON		DIN03080-N/1
5	GASKET	1	SILICONE RUB		DGK00045-N/1
4	CONTACT	1	MBsBD C3604BD-F	Silver Plate (3μm)	DCT04057-5/1
3	CONTACT	1	MBsBD C3604BD-F	Silver Plate (3μm)	DCT04056-5/1
2	CONTACT	1	BeCu C17300	Silver Plate (5μm)	DCT03815-5/1
1	BODY	1	MBsBD C3604BD-F	SUCO Plate	DBD04543-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

ELECTRICAL DATA :

1. IMPEDANCE : 50ohm (Nominal)
2. FREQUENCY RANGE : DC~3GHz
3. PIMD (-43dBm / 2tone) 3rd Order IMD :-160dBc (Min)

TOLERANCE	Decimal ±0.1	DATE 2019. 09. 09.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle ±1°	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE 4.3-10 DIN50 SOLDER END JS-4H
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	2/1	DWG NO. CN03874-7/1 REVISION I R SHEET 1 of 1
		UNIT	mm	

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